



100% Material Declaration Data Sheet FF665

PK229 (v1.0) September 24, 2007

Material Declaration Data Sheet

Average Weight: 5.6330 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.322090	5.718%
	Silicon	7440-21-3	100.00		0.322090	
Solder Bump					0.018510	0.329%
	Tin	7440-31-5	63.00		0.011661	
	Lead	7439-92-1	37.00		0.006849	
Underfill					0.056000	0.994%
	Silica	60676-86-0	70.00		0.039200	
	Epoxy Resin A	9003-36-5	20.00		0.011200	
	Epoxy Resin B	25068-38-6	3.00		0.001680	
	Hardener	19900-65-3	7.00		0.003920	
Heat Spreader					2.800000	49.707%
	Copper	7440-50-8	99.60		2.788800	
	Nickel	7440-02-0	0.40		0.011200	
Heat Spreader Adhesive					0.062000	1.101%
	Organopolysiloxane mixture	N/A	100.00		0.062000	
Substrate					1.818880	32.290%
	Cu	7440-50-8	46.91	metal layer	0.853237	
	Ni	7440-02-0	0.52	metal layer	0.009458	
	Au	7440-57-5	0.12	metal layer	0.002183	
	Glass fiber	NA	10.50		0.190982	
	Halogen fire retardant	NA	5.25		0.095491	
	BT (core)	NA	28.00		0.509286	
	Solder mask	NA	8.70		0.158243	
Solder Balls					0.555520	9.862%
	Tin	7440-31-5	63.00		0.3499776	
	Lead	7439-92-1	37.00		0.2055424	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
09/24/07	1.0	Initial release.